



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE75004-EPD	Issued	17. May 2021
MA#	MA005418247		
Package	PG-TSDSO-14-41	Weight*	64.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.299	2.00	2.00	20033	20033
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		144	
	non noble metal	zinc	7440-66-6	0.037	0.06		575	
	non noble metal	iron	7439-89-6	0.745	1.15		11490	
	non noble metal	copper	7440-50-8	30.247	46.66	47.88	466550	478759
wire	non noble metal	copper	7440-50-8	0.484	0.75	0.75	7461	7461
encapsulation	organic material	carbon black	1333-86-4	0.087	0.13		1338	
	plastics	epoxy resin	-	3.382	5.22		52169	
	inorganic material	silicondioxide	60676-86-0	25.439	39.24	44.59	392384	445891
leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25322	25322
plating	noble metal	silver	7440-22-4	0.823	1.27	1.27	12688	12688
glue	plastics	epoxy resin	-	0.112	0.17		1723	
	noble metal	silver	7440-22-4	0.527	0.81	0.98	8123	9846
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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